

## Wire Wound Chip Common Mode Choke Coils

### Feature

- \* Minature Size,Suitable For SMT.
- \* ;
- \* Nusing With Large Coupling Coefficient,Little Impact On High-speed Differential Signal; Prevention Of Common Mode Noise At High Frequency.
- \* 67 2200
- \* 67 2200 Are Optional For Different Noise Level And Signal Frequency.



### Application

- \* USB  
USB Lines Of PC,Peripheral Equipments.
- \* LCD LVDS  
LVDS Lines Of Note PC,LCD.
- \* AV USB  
USB Lines Of Small Digital AV Equipment,etc.

### Part Number

CMC 0805 S 900 T

#### Product Typel

CMC

FHW: Wire Wound Chip Common Mode Choke Coils Series

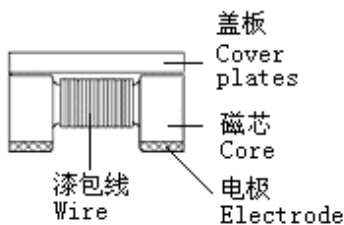
Dimensions 0805(2.0×1.2mm) 1206(3.2×1.6mm)

Desing Symbol S— Magnetically Shielded

Impedance 900=90 371=370 102=1000

Packaging T: Tape & Reel B: Bulk

### Product Structure



**Dimension**

Unit mm

Size	L	W	T	A	B
0805	2.0±0.2	1.2±0.2	1.2±0.2	0.45	0.45
1206	3.2±0.2	1.6±0.2	1.8±0.2	0.6	0.6

**ELECTRICAL CHARACTERISTICS**

0805 Type

Part NO.	Common Mode Impedance @100MHz( )	Rdc( ) Max	Idc(mA) Max	Vdc(V) Max	IR(M ) min
CMC0805S-670T	67± 25%	0.25	400	50	10 10

**Reliability Test Method**

No.	Items	Requirements	Test Methods and Remarks										
1	Solder ability	No visible mechanical damage.  Electrode surface solder coverage. CMC series 80%	245±5 96.5%Sn/3.0%Ag/0.5%Cu 5±1s Dip pads in flux and dip in solder pot(96.5Sn/3.0Ag/0.5Cu)at 245±5 for 5±1s.										
2	Resistance to Soldering	No visible mechanical damage. ±20 Impedance shall not change more than ±20%.	260±5 96.5%Sn/ 3.0%Ag/0.5%Cu 10±1s Dip pads in flux and dip in solder pot(96.5Sn/3.0Ag/0.5Cu)at 260±5 for 10±1s.										
3	Vibration	No visible mechanical damage. ±20 Impedance shall not change more than ±20%.	1.5mm 10~55Hz (X Y Z) 2 Inductors shall be subjected to vibration of 1.5mm amplitude frequency 10~55Hz (10Hz to 55Hz to 10Hz in a period of 1 minute) for 2h in each of three(X Y Z) axes.										
4	Adhesion of electrode	The end electrode did not fall off after the test.  No visible mechanical damage.	PCB Weld the product on the PCB board, and apply force as shown in the diagram, direction and requirement.  <table border="1" data-bbox="986 1464 1457 1686"> <thead> <tr> <th>Size</th> <th></th> </tr> </thead> <tbody> <tr> <td>0805 Series</td> <td>5 N</td> </tr> <tr> <td>1206 Series</td> <td>10 N</td> </tr> <tr> <td colspan="2">Keep time: (10±1)s</td> </tr> <tr> <td colspan="2">Speed: 1.0 mm/s.</td> </tr> </tbody> </table>	Size		0805 Series	5 N	1206 Series	10 N	Keep time: (10±1)s		Speed: 1.0 mm/s.	
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Keep time: (10±1)s													
Speed: 1.0 mm/s.													
5	Low temperature resistance	No visible mechanical damage. ±20 Impedance shall not change more than ±20%.	-40± 2 1000 <sup>24</sup> / <sub>E0</sub> h Component shall be subjected to -40± 2 for 1000 <sup>24</sup> / <sub>E0</sub> h.										

6	High temperature resistance	<p>No visible mechanical damage.</p> <p style="text-align: center;"><math>\pm 20</math></p> <p>Impedance shall not change more than <math>\pm 20\%</math>.</p>	<p style="text-align: center;"><math>-85 \pm 2</math>                      <math>1000 \overset{24}{\underset{E0}{h}}</math></p> <p>Component shall be subjected to <math>-85 \pm 2</math> for <math>1000 \overset{24}{\underset{E0}{h}}</math>.</p>
7	Temperature Shock	<p>No visible mechanical damage.</p> <p style="text-align: center;"><math>\pm 20</math></p> <p>Impedance shall not change more than <math>\pm 20\%</math>.</p>	<p style="text-align: center;">+85 30                      -40 30                      100</p> <p>+85 30minutes 8 : -40 30minutes 100 Cycles.</p>
8	High temperature load	<p>No visible mechanical damage.</p> <p style="text-align: center;"><math>\pm 20</math></p> <p>Impedance shall not change more than <math>\pm 20\%</math>.</p>	<p style="text-align: center;"><math>85 \pm 2</math>                      <math>1000 \overset{24}{\underset{E0}{h}}</math></p> <p>shall be store at <math>85 \pm 2</math> for <math>1000 \overset{24}{\underset{E0}{h}}</math> with rated current applied.</p>
9	Static Humidity	<p>No visible mechanical damage.</p> <p style="text-align: center;"><math>\pm 20</math></p> <p>Impedance shall not change more than <math>\pm 20\%</math>.</p>	<p style="text-align: center;">90% 95%,                      <math>60 \pm 2</math>                      <math>1000 \overset{24}{\underset{E0}{h}}</math></p> <p>h</p> <p>shall be subjected to 90% 95%RH, at <math>60 \pm 2</math> for <math>1000 \overset{24}{\underset{E0}{h}}</math></p>
10	Bending strength	<p>No visible mechanical damage.</p>	<p style="text-align: center;">Install the inductor on the test substrate; Apply force in the vertical direction (as shown below).</p> <p style="text-align: center;"><math>1 \pm 0.5</math> mm/s                      <math>2 \pm 0.2</math> mm</p> <p style="text-align: center;"><math>20 \pm 1</math> s                      The epoxy plate should bend down to <math>2 \pm 0.2</math> mm at the bending rate of <math>1 \pm 0.5</math> mm/s                      Keep time <math>20 \pm 1</math> sec.</p>



**Packaging**

\* Taping drawings

\* Reel dimensions (Unit:mm)

Part NO.	- \$ typ.	- %typ.	- & typ.	D typ.
0805-1206	178	60	13	8.4

\* Leader and blank portion

\* Taping dimensions (Unit: mm)

EMBOSED tape

Part NO.	W	E	F	D0	D1	P0	P1	P2	P0×10	t	A0	B0	K0
0805	8.00	1.75	3.50	1.50	0.65	4.00	4.00	2.00	40.00	0.23	1.50	2.25	1.40
1206	8.00	1.75	3.50	1.50	0.65	4.00	4.00	2.00	40.00	0.23	1.90	3.55	2.00

\*